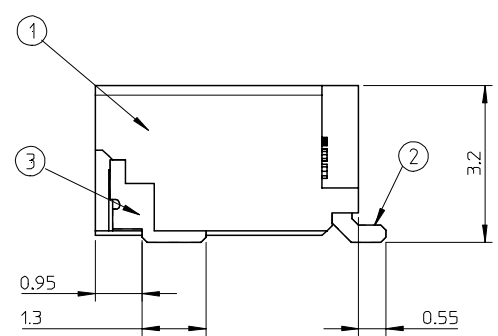
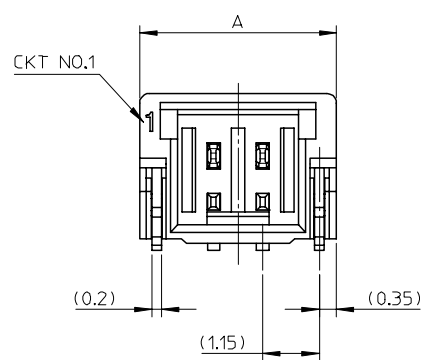


参考パターンレイアウト
RECOMMENDED PATTERN DIM.(REF)
SCALE:5-1



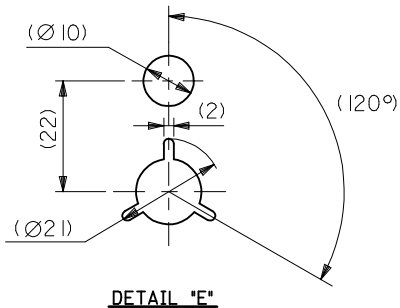
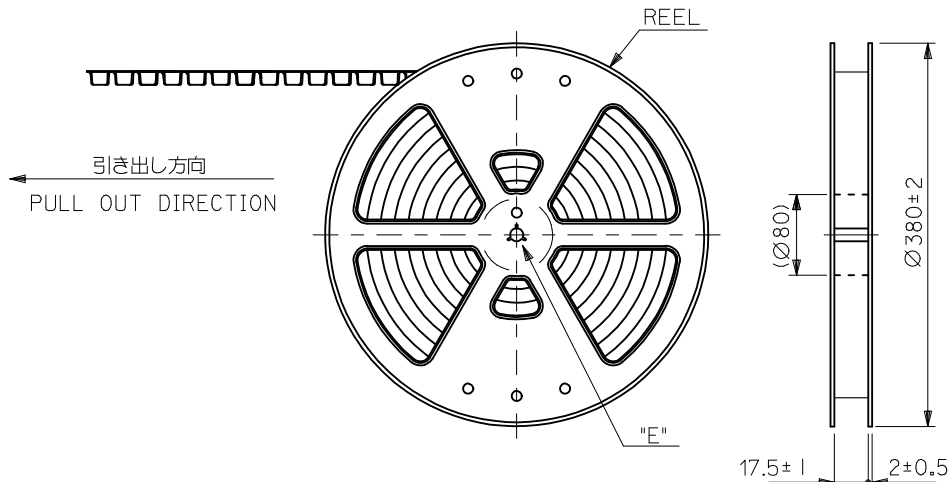
番号 NO.	部品 PART	材質 MATERIAL
①	ウェハー WAFER	耐熱ナイロン、UL94V-0、色：自然色 HEAT RESISTANCE NYLON, UL94V-0, COLOR:NATURAL
②	ソルダーピン SOLDER PIN	リン青銅 PHOSPHOR BRONZE すずメッキ : 1 MICRO METER MINIMUM. TIN PLATING ニッケル下地メッキ : 1 MICRO METER MINIMUM. NICKEL UNDER PLATING
③	ネイル NAIL	黄銅 BRASS すずメッキ : 1 MICRO METER MINIMUM. TIN PLATING ニッケル下地メッキ : 1 MICRO METER MINIMUM. NICKEL UNDER PLATING

4.0	7.0	501568-0509	5	501568-**09
3.0	6.0	501568-0409	4	
2.0	5.0	501568-0309	3	
1.0	4.0	501568-0209	2	
B	A	MATERIAL NO.	CKT	MODEL NO.

NOTES

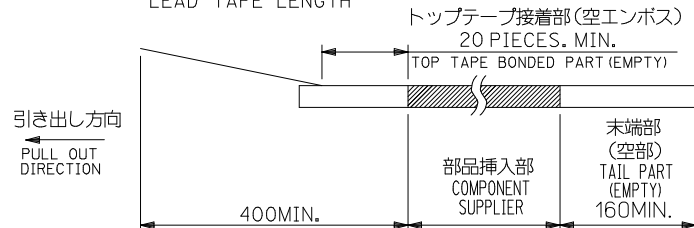
1. かん合相手 : 501330-****
MATE WITH : 501330-****
2. ソルダーピン及びネイルの平坦度は0.1MAX.
SOLDER PIN AND NAIL COPLANARITY TO BE 0.1MAX.
- ③ 極数=偶数に適用
APPLY FOR CKT SIZE=EVEN
4. 6~15極は、SD-501568-002を参照下さい。
REFER TO SD-501568-002 ABOUT 6-15CKT.

REVISED EC NO: J2008-0220 DRW: NABEI 2007/07/25 CHK: KYOYODA 2007/07/27 APP: NUKITA 2007/07/27	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY	SCALE 10:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	10 UNDER	±0.2	DRAWN BY AMIZUMURA	DATE 2005/01/19	TITLE 1.0 WIRE TO BOARD CONN. 1-ROW R/A WAFER ASSY 2-5CKT -LEAD FREE-	
	10 OVER 30 UNDER	±0.25	CHECKED BY MYAGI	DATE 2005/01/19	MOLEX INCORPORATED	
	30 OVER	±0.3	APPROVED BY ANODA	DATE 2005/01/19	DOCUMENT NO. SD-501568-001	SHEET NO. 1 OF 1
	ANGULAR	±3 °	MATERIAL NO.		SEE TABLE	
	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			

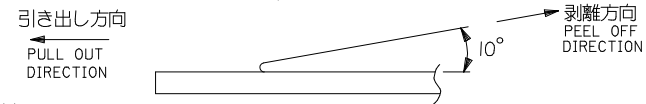


NOTES

- 製品詳細寸法は製品単体図面を参照して下さい。
FOR DETAIL OF CONNECTOR DIMENSIONS, PLEASE SEE THE DRAWING OF CONNECTOR ITSELF (NOT PACKAGED).
- 梱包数量：1700個/リール
NUMBER OF CONNECTORS：1700PIECES/REEL
- リードテープ長さ
LEAD TAPE LENGTH

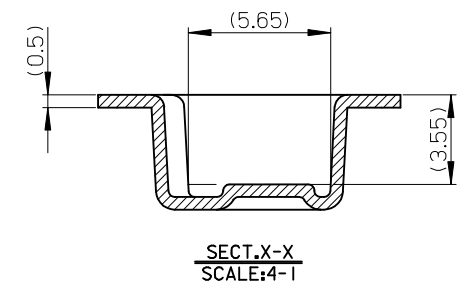
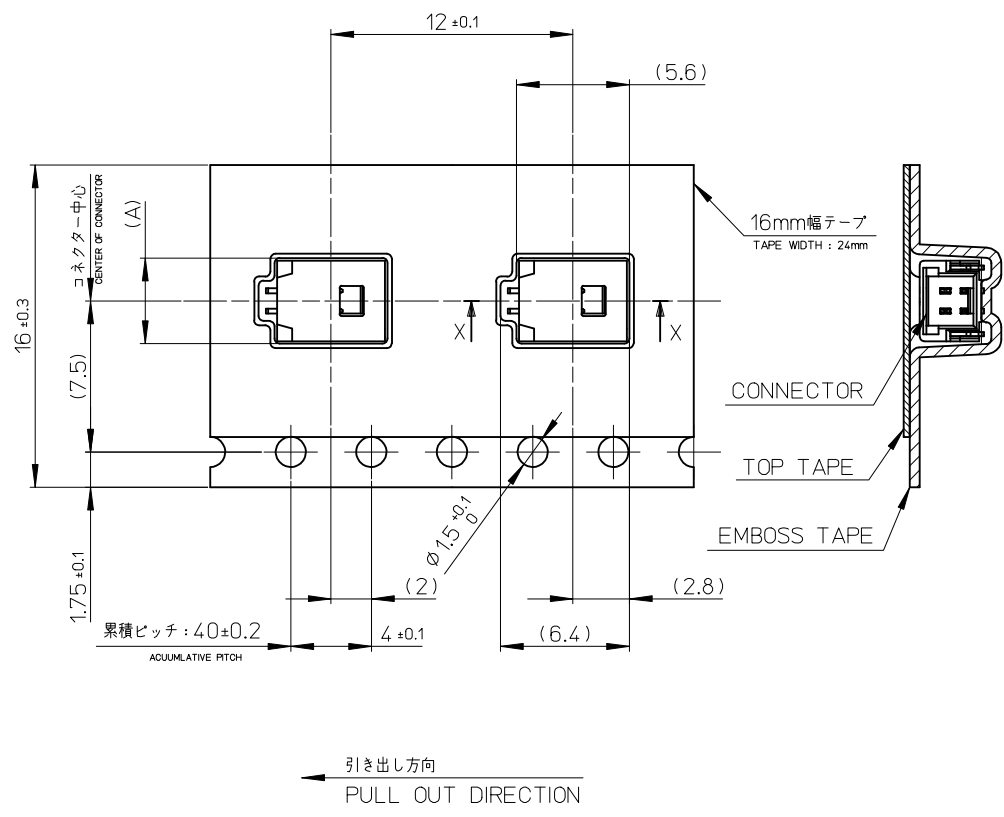


- トップテープの剥離強度：0.1~1.3N(10.2~132.5gf) (剥離方向は下図参照)
PEELING OFF FORCE OF TOP TAPE (PEELING DIRECTION AS SHOWN IN FOLLOWING FIGURE)
尚、本規格値は、出荷時に適用。(但し、輸送時に剥離が発生しないこと)
THIS REQUIREMENT SHOULD BE APPLIED AT SHIPMENT.
PEEL OFF SHOULD NOT BE ALLOWED, DURING TRANSPORTATION.



- 材料
MATERIAL
キャリアテープ：ポリプロピレン
CARRIER TAPE: POLYPROPYLENE
トップテープ：PET, PE, REF
TOP TAPE
リール：ポリスチレン (リサイクル材を含む)
REEL: POLYSTYRENE (RECYCLE MATERIAL CONTAINED)
- ELV及びRoHS適合品。
ELV AND RoHS COMPLIANT.

REVISED EC NO.: J2009-0951 DRW: KTOYODA 2008/10/29 CHKD: MATSUMOTO 2008/10/29 APPR: NUKITA 2008/10/29	DESCRIPTION REV	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
		10 UNDER	±0.2	DRAWN BY AMIZUMURA	DATE 2005/11/26	TITLE 1.0 WIRE TO BOARD CONN. WAFER ASS'Y (1-ROW R/A) EMBTP PKG -LEAD FREE-				
		10 OVER 30 UNDER	±0.25	CHECKED BY MYAGI	DATE 2005/11/26	MOLEX INCORPORATED				
		30 OVER	±0.3	APPROVED BY ANODA	DATE 2005/11/26	MATERIAL NO. SEE SHEET 2 DOCUMENT NO. SD-501568-005 SHEET NO. 1 OF 2				
A	REV	ANGULAR ±1 ° DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION						



7.3	501568-0509	501568-0507	5
6.3	501568-0409	501568-0407	4
5.3	501568-0309	501568-0307	3
4.3	501568-0209	501568-0207	2
(A)	CONNECTOR	MATERIAL NO.	CKTS.

REVISED EC NO: J2009-0951 DRWK:TOYODA 2008/10/29 CHKD:MATSUMOTO 2008/10/29 APPR:NUKITA 2008/10/29	DESCRIPTION A	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
		10 UNDER	±0.2	DRAWN BY AMIZUMURA	DATE 2005/11/26	TITLE 1.0 WIRE TO BOARD CONN. WAFER ASS'Y (1-ROW R/A) EMBTP PKG -LEAD FREE-			
		10 OVER 30 UNDER	±0.25	CHECKED BY MYAGI	DATE 2005/11/26	MOLEX INCORPORATED			
		30 OVER	±0.3	APPROVED BY ANODA	DATE 2005/11/26	DOCUMENT NO. SD-501568-005			
		ANGULAR	±3 °	MATERIAL NO. SEE CHART		SHEET NO. 2 OF 2			
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					